**5 per test**

A testing structure will be constructed to allow 5 chips to be tested at one time, as well as to get equal amounts of power to be transmitted to the devices under test. Under the constraint that PCB lengths and width dimensions do not exceed , and that there is a gap on either side of the PCBs, 2 pentagons extruded to with a diameter of from a vertex to the opposite side will be 3D printed from a non-conductive plastic. The radial antenna producing RF emissions will be positioned in the geometric center of the decagon, split evenly down the height of the extruded decagon. 1 PCB per side will be attached on the inside of the pentagon using non-conductive clamps to receive treatments. While one pentagon is being used for testing, the other decagon will be populated with the next set of boards to be tested.

**10 per test**

A testing structure will be constructed to allow multiple chips to be tested at one time, as well as to get equal amounts of power to be transmitted to the devices under test. Under the constraint that PCB lengths and width dimensions do not exceed , and that there is a gap on either side of the PCBs, 2 decagons extruded to with a diameter of from vertex to opposite vertex will be 3D printed from a non-conductive plastic. The radial antenna producing RF emissions will be positioned in the geometric center of the decagon, split evenly down the height of the extruded decagon. 1 PCB per side will be attached to the insides of the decagon using non-conductive clamps to receive treatments. While one decagon is being used for testing, the other decagon will be populated with the next set of board to be tested.